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RoHS Certificate of Compliance

Issue 11-2026

BREL International herewith confirms that RoHS-compliant BREL products are conforming to the following EU directives:

EU directive 2011/65/EU (RoHS Recast, June 8, 2011 incl. dir. 2015/863/EU) and EU directive 2003/11/EC (restrictions of certain dangerous substances and preparations).

Following restricted materials are not used and do not exceed the legal limits:

- Lead (Pb, see exemptions) 2011/65/EU
- Cadmium (Cd) 2011/65/EU
- Polybrominated biphenyls (PBB) 2011/65/EU
- Decabromodiphenyl ether (DecaBDE) 2003/11/EC
- Octabromodiphenyl ether (OctaBDE) 2003/11/EC
- Butyl benzyl phthalate (BBP) 2015/863/EU
- Diisobutyl phthalate (DIBP) 2015/863/EU
- Mercury (Hg) 2011/65/EU
- Chromium (Cr VI) 2011/65/EU
- Polybrominated diphenyl ethers (PBDE) 2011/65/EU
- Pentabromodiphenyl ether (PentaBDE) 2003/11/EC
- Bis(2-ethylhexyl) phthalate (DEHP) 2015/863/EU
- Dibutyl phthalate (DBP) 2015/863/EU

Exemptions: The following exemptions according to RoHS Annex III (EU 2025/2363; EU 2025/1802) are applicable:

7a (expires June 30, 2027) and 7a-III (expires December 31, 2027): Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead). Thick film resistor series HVM, HVR, HVT and GST.

7c-I (expires June 30, 2027): Electrical and electronic components containing lead in a glass or ceramic, or in a glass or ceramic matrix compound. Thick film chip resistor series CHR, CHS, CHM, CHK, CHP, CRA, CRB, CRS, CRM, CBW and CDV.

7c-V (expires December 31, 2027): Electrical and electronic components containing lead in a glass or glass matrix compound for use as a resistive material such as ink, with a resistivity range from 1 Ω/square to 100 MΩ/square. Thick film resistor series HVM, HVR, HVT and GST.

7c-II (expires December 31, 2027): Lead in dielectric ceramic in capacitors. MLCC.

The components are suitable for a lead-free process according to EN 60068-2-58 and in accordance with the IPC/JEDEC standard J-Std-020.

The lead-free process has been tested using solder alloy Sn96.5Ag3Cu0.5



